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# **Digital Research and Development of Materials and Processes**

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Deadline for manuscript submissions:

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### **Message from the Guest Editors**

Dear Colleagues,

Digital research and development technology has become an important tool for the design of materials and processes, and it can significantly reduce the time and costs of research and discovery compared with the traditional trial and error method. It combines the advanced idea of integrated computational materials engineering (ICME) and material genome initiative (MGI), and applies those digital technologies into material and process research, e.g., ICME platform, multiscale modelling, material database, machine learning, artificial intelligence (AI), 3D printing, high-throughput experiment, etc. These digital research and development approaches could enable an improved understanding and prediction of the microstructure. mechanical properties and service behavior of materials

This Special Issue, entitled "Digital Research and Development of Materials and Processes", aims to collect the most recent research on digital technologies applied in the design of materials and processes, and it welcomes original research papers, reviews, and case studies on topics including











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### **Editor-in-Chief**

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## **Message from the Editor-in-Chief**

Processes (ISSN 2227-9717) provides an advanced forum for process/system-related research in chemistry, biology, material, energy, environment, food, pharmaceutical, manufacturing and allied engineering fields. The journal publishes regular research papers, communications, letters, short notes and reviews. Our aim is to encourage researchers to publish their experimental, theoretical and computational results in as much detail as necessary. There is no restriction on paper length or number of figures and tables.

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